

## SP4024 Series 1.3pF, 7A Discrete TVS Diode



### Description

The SP4024 series integrates low capacitance steering diodes with one or two avalanche breakdown diodes for unidirectional or bidirectional protection, respectively, to protect against ESD and lightning induced surge events. These devices can safely absorb up to 7A per IEC 61000-4-5 2<sup>nd</sup> Edition ( $t_p=8/20\mu s$ ) without performance degradation and a minimum  $\pm 30kV$  ESD per IEC 61000-4-2 International Standard. The low loading capacitance and high surge capability make it ideal for protecting telecommunication ports such as xDSL and other high voltage, high speed legacy interfaces.

### Pinout

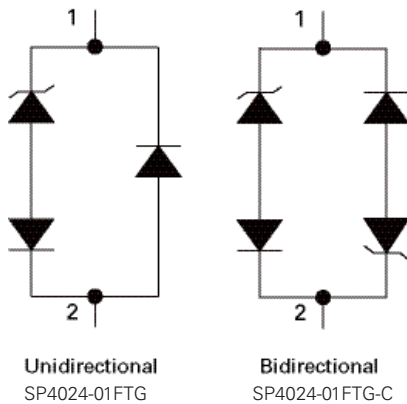


Cathode polarity for unidirectional only

### Features

- ESD, IEC 61000-4-2,  $\pm 30kV$  contact,  $\pm 30kV$  air
- EFT, IEC 61000-4-4, 40A (5/50ns)
- Lightning, IEC 61000-4-5 2<sup>nd</sup> Edition, 7A ( $t_p=8/20\mu s$ )
- Low capacitance of 1.3pF (@  $V_R=0V$ )
- Low leakage current
- Unidirectional and Bidirectional configuration
- Small SOD323 package fits 0805 footprints
- AEC-Q101 qualified
- Halogen free, Lead free, and RoHS Compliant
- Moisture Sensitivity Level (MSL-1)

### Functional Block Diagram



### Applications

- xDSL Interfaces
- RS-232
- RS-485
- Power Ports
- Security Equipment
- Instrumentation
- Medical Equipment
- Computers and Peripherals

### Additional Information



Life Support Note:

**Not Intended for Use in Life Support or Life Saving Applications**

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$I_{PP}$	Peak Current ( $t_p=8/20\mu s$ )	7	A
$P_{PK}$	Peak Pulse Power ( $t_p=8/20\mu s$ )	350	W
$T_{OP}$	Operating Temperature	-40 to 150	°C
$T_{STOR}$	Storage Temperature	-55 to 150	°C

Note:

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### Electrical Characteristics ( $T_{OP}=25^\circ C$ )

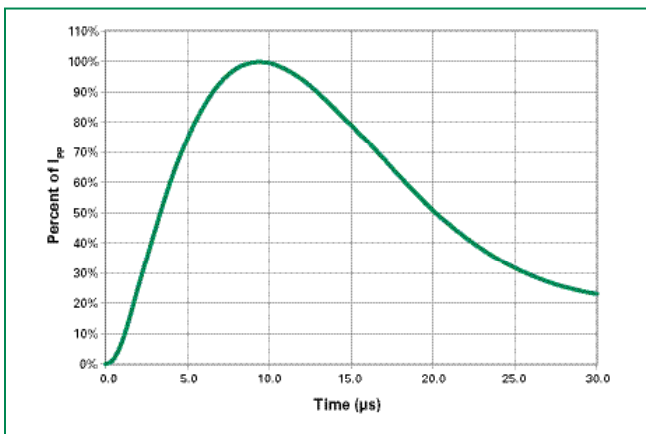
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	$V_{RWM}$	$I_R \leq 1\mu A$ with Pin 1 to Pin 2			24	V
Breakdown Voltage	$V_{BD}$	$I_T=1mA$ with Pin 1 to Pin 2	26			V
Leakage Current	$I_{LEAK}$	$V_R=24V$ with Pin 1 to Pin 2			0.5	$\mu A$
Clamp Voltage <sup>1</sup>	$V_C$	$I_{PP}=1A, t_p=8/20\mu s$ , Fwd		34		V
		$I_{PP}=2A, t_p=8/20\mu s$ , Fwd		36		V
		$I_{PP}=5A, t_p=8/20\mu s$ , Fwd		43		V
		$I_{PP}=7A, t_p=8/20\mu s$ , Fwd		48	50	V
Dynamic Resistance <sup>2</sup>	$R_{DYN}$	TLP $t_p=100ns$ , Pin 1 to Pin 2		0.7		$\Omega$
ESD Withstand Voltage <sup>1</sup>	$V_{ESD}$	IEC61000-4-2 (Contact Discharge)	$\pm 30$			kV
		IEC61000-4-2 (Air Discharge)	$\pm 30$			kV
Diode Capacitance <sup>1</sup>	$C_D$	Reverse Bias=0V, $f=1MHz$ , Pin 1 to Pin 2		1.3	2	pF

Note:

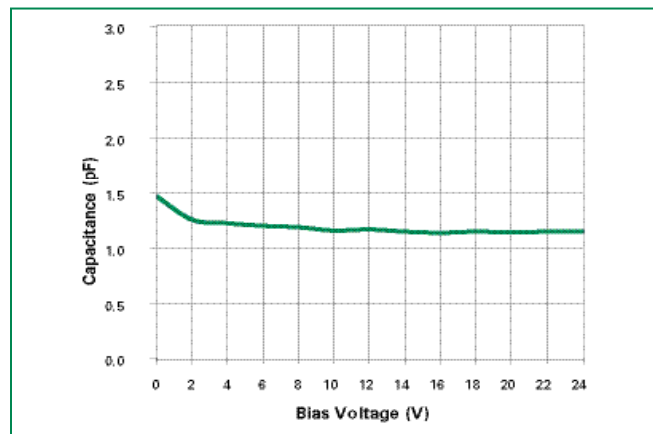
<sup>1</sup>Parameter is guaranteed by design and/or component characterization.

<sup>2</sup>Transmission Line Pulse (TLP) test setting : Std.TDR(50 $\Omega$ ), $t_p=100ns$ ,  $t_r=0.2ns$  ITLP and VTLP averaging window: start1=70ns to end t2=80ns

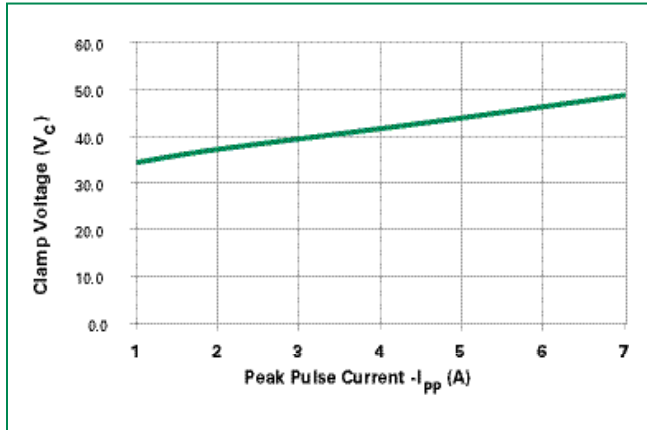
### 8/20 $\mu s$ Pulse Waveform



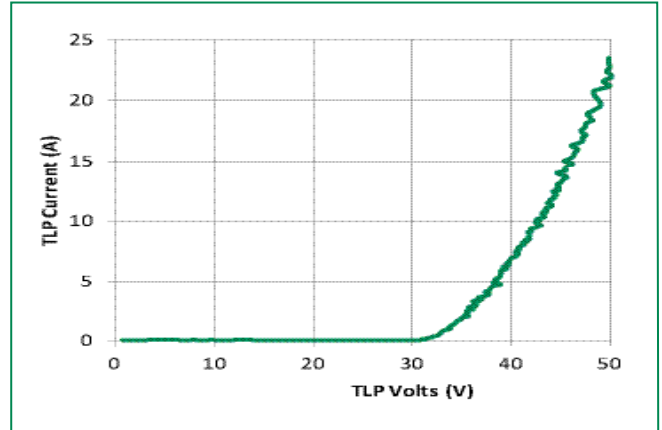
### Capacitance vs. Reverse Bias (Pin 1 to Pin 2)



**Clamping Voltage vs. Peak Pulse Current (Pin 1 to Pin 2)**

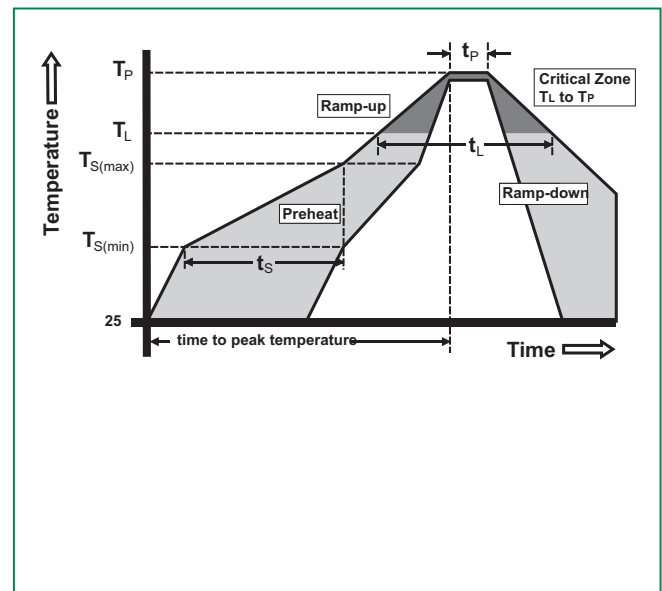


**Transmission Line Pulsing (TLP) Plot (Pin 1 to Pin2)**



**Soldering Parameters**

Reflow Condition	Pb – Free assembly	
Pre Heat	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 – 180 secs
Average ramp up rate (Liquidus) Temp ( $T_L$ ) to peak	3°C/second max	
$T_{s(max)}$ to $T_L$ - Ramp-up Rate	3°C/second max	
Reflow	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Temperature ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_p$ )	260 <sup>+0/-5</sup> °C	
Time within 5°C of actual peak Temperature ( $t_p$ )	20 – 40 seconds	
Ramp-down Rate	6°C/second max	
Time 25°C to peak Temperature ( $T_p$ )	8 minutes Max.	
Do not exceed	260°C	



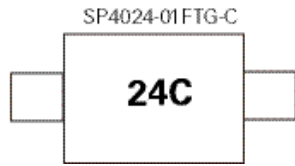
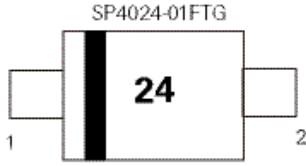
**Product Characteristics**

<b>Lead Plating</b>	Matte Tin
<b>Lead Material</b>	Copper Alloy
<b>Lead Coplanarity</b>	0.0004 inches (0.102mm)
<b>Substrate material</b>	Silicon
<b>Body Material</b>	Molded Compound
<b>Flammability</b>	UL Recognized compound meeting flammability rating V-0

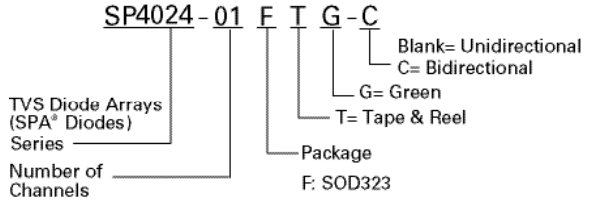
Notes :

1. All dimensions are in millimeters
2. Dimensions include solder plating.
3. Dimensions are exclusive of mold flash & metal burr.
4. Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
5. Package surface matte finish VDI 11-13.

**Part Marking System**



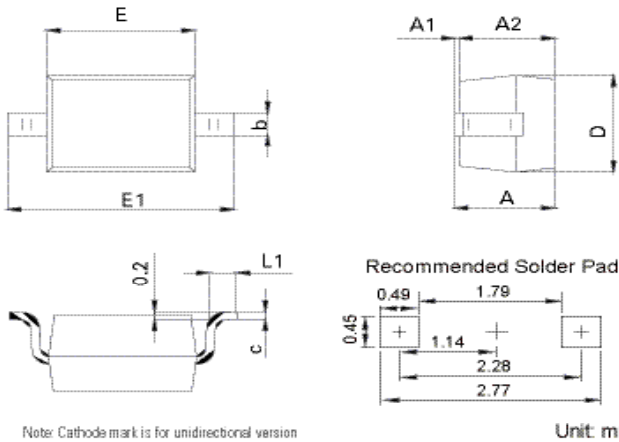
**Part Numbering System**



**Ordering Information**

Part Number	Package	Marking	Min. Order Qty.
SP4024-01FTG	SOD323	24	3000
SP4024-01FTG-C	SOD323	24C	3000

**Package Dimensions -SOD323**



Symbol	SOD323			
	Millimeters		Inches	
	Min	Max	Min	Max
A	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A2	0.80	0.90	0.031	0.035
b	0.25	0.35	0.010	0.014
c	0.08	0.15	0.003	0.006
D	1.20	1.40	0.047	0.055
E	1.60	1.80	0.063	0.071
E1	2.50	2.75	0.098	0.108
L1	0.22	0.40	0.009	0.016

**Embossed Carrier Tape & Reel Specification – SOD323**

Symbol	Dimensions (mm)
A0	1.46 +/- 0.1
B0	2.90 +/- 0.1
W	8.0 +0.3/- 0.10
D0	1.50 +0.1
D1	0.45~1.15
E1	1.75 +/- 0.10
E2	-
F	3.50 +/- 0.10
P0	4.0 +/- 0.10
P	4.0 +/- 0.10
P1	2.0 +/- 0.05
K0	1.25 +/- 0.1
T	0.254 +/- 0.02

